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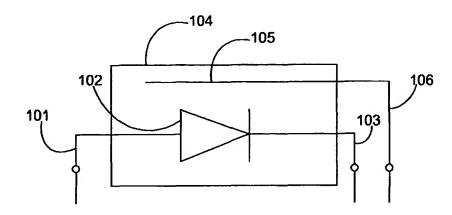
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(54) Title: METHOD AND ARRANGEMENT FOR SHIELDING A COMPONENT AGAINST ELECTROSTATIC INTERFER-**ENCE**



(57) Abstract: The invention relates to an apparatus and arrangement for shielding a component, particularly a semiconductor component, against electrostatic discharge. The semiconductor component (102, 202, 302) according to an embodiment of the invention comprises an electroconductive element (105, 205, 305), for which there is arranged at least one outlet (106, 206, 306) so that the electroconductive element (105, 205, 305) is groundable through said outlet (106, 206, 306) for shielding the semiconductor component (102, 202, 302) against electrostatic pulses.

